APPLICA	BLE STAN	NDARD								
Operating Temperature D		D	-55 °C to 85 °C	C ⁽¹⁾		rage	- D	-10 °C to	60 °C	(2)
Rating	Temperature Range Voltage		Signal Contact : 50 V AC			mperature Range prage Humidity Range		10 0 10		
	Current		Power Contact : 200 V AC					Relative humidity 8	5% max	
						perating Humidity Range (Not dewed				
					TION					
.,,			SPECI	FICF	TION	<u> </u>	DEOL	IDEMENTO	ОТ	T A =
CONSTR	TEM		TEST METHOD				REQU	IREMENTS	QT	АТ
General Exa		Vieually	and by measuring instrument.		-	Accord	ling to drawin	n	×	×
	Marking		Confirmed visually.				ing to drawin	y.	×	×
ELECTRIC CHARAC			TERISTICS						ı	
Contact Resistance		100 mA(DC or 1000Hz)				Signal Contact : $70m\Omega$ MAX. Power Contact : $20m\Omega$ MAX.			×	_
Insulation Resistance		Signal Contact : 100 V DC.				Signal Contact : 100 MΩMIN.				
		Power Contact : 250 V DC 1				Power Contact : 1000 MΩ MIN. 1				
Voltage Proof		Signal Contact : 150 V AC for 1 min.				No flashover or breakdown.				×
		Power Contact : 600 V AC for 1 min. 1								
	ICAL CHAP					la a a att	- F	40 NI MANY A	×	_
Insertion and Withdrawal Forces		Measured by applicable connector.				Insertion Force: 18 N MAX.1 Withdrawal Force: 2 N MIN.				_
Mechanical Operation		100 time	100 times insertions and extractions.			① Contact Resistance:			×	 -
							Signal Contact: 80m Ω MAX. Power Contact: 30m Ω MAX. No damage, crack and looseness of parts.			
		F								
Vibration		Frequency 10 to 55 to 10Hz, approx 5min Single amplitude: 0.75 mm, 10 cycles for 3 axial directions.				 No electrical discontinuity of 1 μs. No damage, crack and looseness of parts. 				_
Shock			490 m/s ² , duration of pulse 11 ms						×	<u> </u>
			s for 3 both axial directions.							
	IMENTAL (TERISTICS			_				
Damp Heat (Steady state)		Exposed	Exposed at 40±2 °C, 90 ~ 95 %, 96 h.			_	ntact Resistar		×	-
Rapid Change of		Tempera	Temperature -55 → +85 °C			Signal Contact : $80m \Omega$ MAX. Power Contact : $30m \Omega$ MAX.			×	+-
Temperature		Time					ulation Resist			
		under 5	•				Signal Contac			
		(Relocation time to chamber : within 2~3 MIN)				1000 MΩ MIN. 3 No damage, crack and looseness of parts.				
Cold		Exposed	Exposed at -55°C, 96 h			① Contact Resistance: Signal Contact: 80m Ω MAX.			×	_
Dry Heat		Exposed at 85°C, 96 h				1 Power Contact: 30m Ω MAX. 2 No damage, crack and looseness of parts.				_
Sulfur Dioxide		Exposed	Exposed at 25±2°C, 75±5%RH, 25 PPM for 96 h.			No defect such as corrosion which impairs				<u> </u>
		(Test star	ndard: IEC 68) 🛕			_	function of co			
							② Contact Resistance:			
							Signal Contactoriactorial			
Resistance to		1)Reflow soldering :				No deformation of case of excessive			×	<u> </u>
Soldering Heat		Peak TMP : 260°CMAX				looseness of the terminal.				
			TMP: 220°CMIN for 60sec	200						
Solderability			2) Soldering irons : 360°C MAX. for 5 sec. Soldered at solder temperature			A new	uniform coati	ng of solder shall cover a	×	╁
			240±3°C for immersion duration, 3 sec.			minimum of 95 % of the surface being immersed.				
COUNT DE		DESCRIPTI	ESCRIPTION OF REVISIONS DESIGNATION DE SIGNATION DESIGNATION DE SIGNATION DE SIGN						DA	ΤΕ
13					TS. 00	ONO		KN. SHIBUYA	15. 0	9. 09
REMARKS (1) Include tempera		rature rise cau	ature rise caused by current-carrying.			APPROVED		HS. OKAWA	14. 09. 0	
	(2) "STORAGE" r before assem	_	eans a long-term storage state for the unused product y to PCB.				CHECKED	KN. SHIBUYA	14. 0	9. 02
		-					DESIGNED	TS. 00N0	14.0	9. 02
Unless otherwise specified, ref			refer to IEC 60512. 🛕			DRAWN TS. 00N0		14. 0	9. 02	
Note QT:Qualification Test AT:As:			urance Test X:Applicable Test		DF	RAWING NO. ELC-35353		ELC-353538-	-00-00	
ЖS		SPECIFICATION SHEET			PART NO.		FX23-40P-0. 5SV15			
11.7	HII	HIROSE ELECTRIC CO., LTD.			CODE NO.		CL573-3002-3-00			1/1

